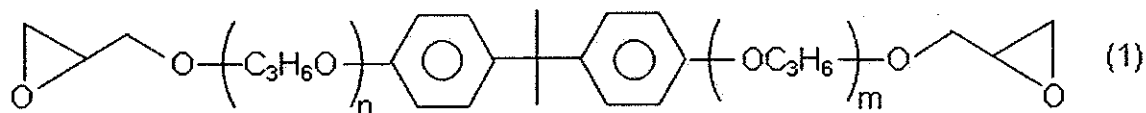


ABSTRACT

Disclosed is a photosensitive adhesive composition including:

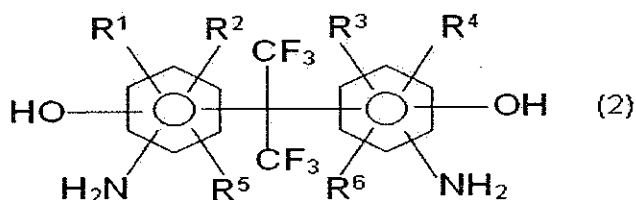
- (A) an epoxy compound,
 - (B) a soluble polyimide having a residue of the diamine represented by the general formula (2),
 - (C) a photopolymerizable compound, and
 - (D) a photopolymerization initiator, wherein
- the epoxy compound (A) contains an epoxy compound represented by the general formula (1), and also the soluble polyimide (B) has a residue of diamine represented by the general formula (2):

[Chemical Formula 1]



wherein m and n in the general formula (1) are integers of 0 or more, which satisfy the relationship: $1 \leq m + n \leq 10$, x is an integer of 1 or more and 5 or less, y is an integer of 1 or more and 10 or less, and $y = 2x$; and

[Chemical Formula 2]



wherein R^1 to R^8 in the general formula (2) may be respectively the same or different, and selected from the group consisting of a hydrogen atom, an alkyl group having 1 to 30 carbon atoms, an alkoxy group having 1 to 30 carbon atoms, a halogen, a sulfone group, a nitro group and a cyano group. The present invention provides a photosensitive adhesive composition which can be developed with an alkali developing solution after exposure, and exhibits high adhesive strength in case of thermocompression bonding on a substrate, and is also excellent in insulation stability.